IPC-7351B

2010

Generic Requirements for Surface Mount Design and Land Pattern Standard

June 2010
Supersedes IPC-7351A
February 2007

A standard developed by IPC

Association Connecting Electronics Industries

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Generic Requirements for Surface Mount Design and Land Pattern Standard

Developed by the Surface Mount Land Patterns Subcommittee (1-13) of the Printed Board Design Committee (1-10) of IPC

Supersedes:

IPC-7351A - February 2007
IPC-7351 - February 2005
IPC-SM-782A with Amendments 1 & 2 - December 1999

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Acknowledgment

Any document involving a complex technology draws material from a vast number of sources. While the principal members of the Surface Mount Land Patterns Subcommittee (1-13) of the Printed Board Design Committee (1-10) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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